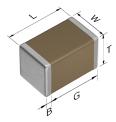
# **Multilayer Ceramic Chip Capacitors**

#### C2012JB1A336M125AC



#### TDK item description C2012JB1A336MT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 75V)	
Series	C2012 [EIA 0805]	
Status	Production	



	Size
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	33µF ±20%	
Rated Voltage	10VDC	
Temperature Characteristic	JB(±10%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	3ΜΩ	

Other	
Soldering Method	Wave (Flow)
Soldening Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

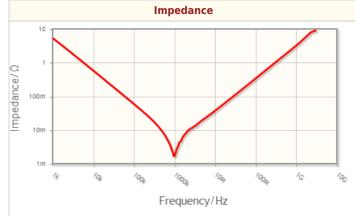
! Images are for reference only and show exemplary products.

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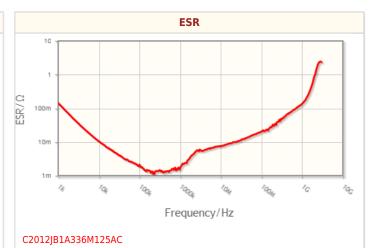
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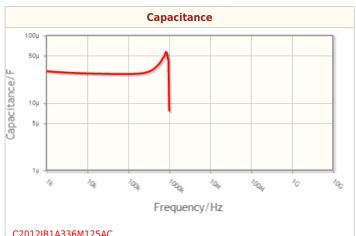


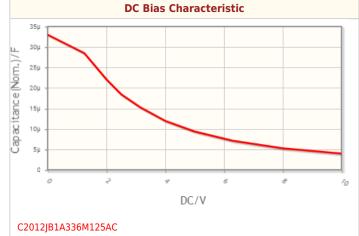


### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

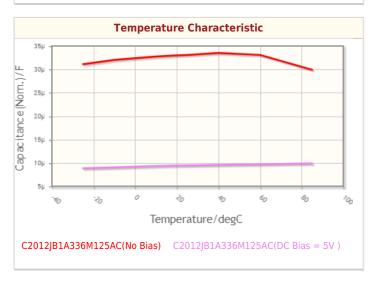


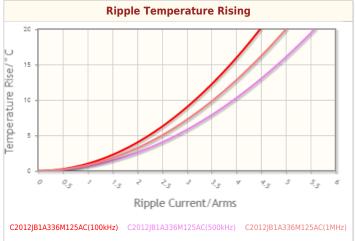
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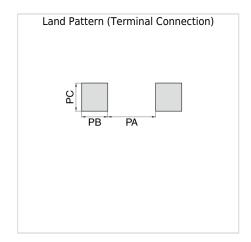
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## C2012JB1A336M125AC



## Associated Images



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